SURFBOARDS[®]



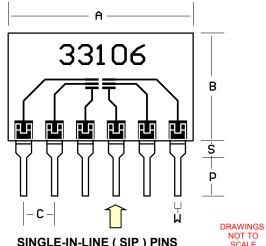
REV A- 10-2011

THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TM

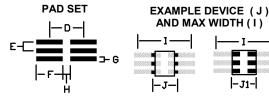
33000 SERIES APPLICATION SPECIFIC ADAPTERS IDS33106

MODEL 33106

6 LEAD .35 mm PITCH DEVICES DEVICE LEAD WIDTH .9, 1.0, To Max 2.2 MM



SINGLE-IN-LINE (SIP) PINS ON .100 in. CENTERS



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

BOARD SPECIFICATIONS



Compliant EC 2002/95

BOARD MATERIAL: .8mm. +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent. CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.

TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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ACCEPTS SOT-963

PARTIAL LISTING

| ON SEMI | ULLGA6 1.0x1.0,0.35P | | |
|------------|--------------------------------------|--|--|
| PANASONIC | SSSMini6-F1 | | |
| TEXAS NST. | DSF (S-PDSO-N6) DSF (S-PX2SON-N6) | | |
| TOSHIBA | CST6, FS6 | | |

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers. Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

| FIG. | ММ | IN. | NOTE: |
|------|-------|------|-----------------------------------|
| Α | 15.24 | .600 | BOARD WIDTH +5mm .020in. |
| в | 8.89 | .350 | BOARD HEIGHT +5mm .020in. |
| С | 2.54 | .100 | SIP PIN SPACE +20mm .008in. |
| D | 1.4 | .055 | PAD CENTERLINE |
| Е | .35 | .014 | DEVICE LEAD PITCH |
| F | 1.1 | .043 | PAD LENGTH |
| G | .2 | .008 | PAD WIDTH |
| н | .3 | .012 | GAP |
| - I | 2.2 | .087 | MAX LEAD WIDTH |
| J | 1.0 | .039 | TYPICAL LEAD WIDTH |
| J1 | .9 | .035 | VARIATION LEAD WIDTH |
| Р | 3.3 | .130 | LENGTH FROM SHOULDER +5mm .020in. |
| S | 1.57 | .062 | PIN SHOULDER HEGHT |
| w | .5 | .020 | PIN WIDTH |

MADE IN USA